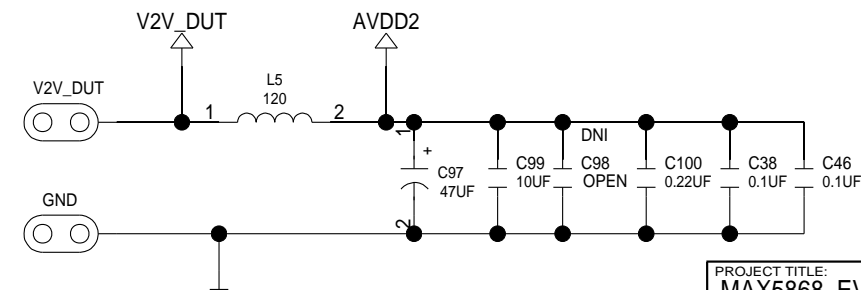
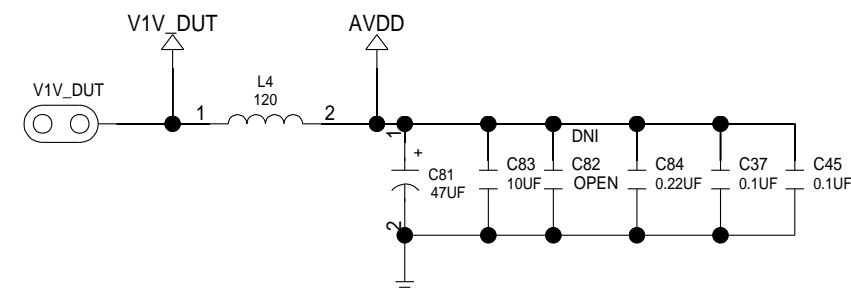
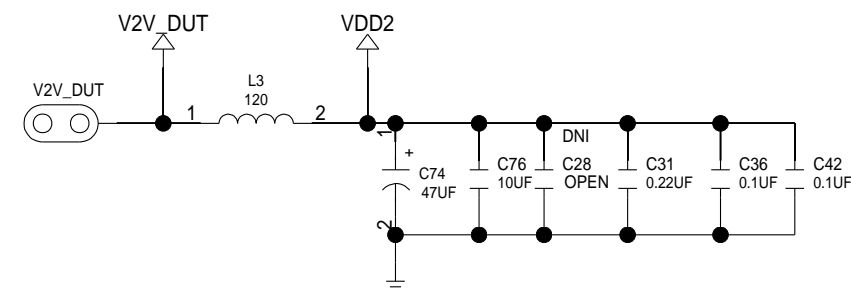
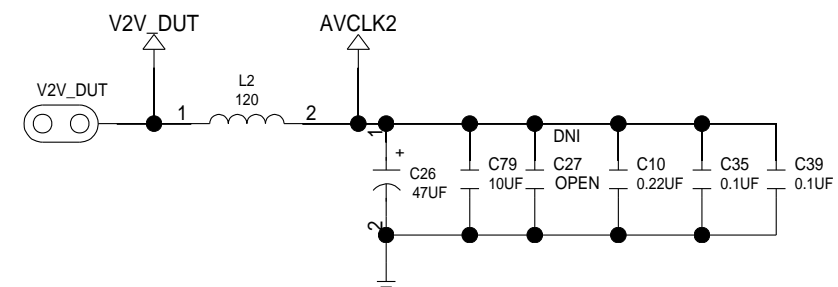
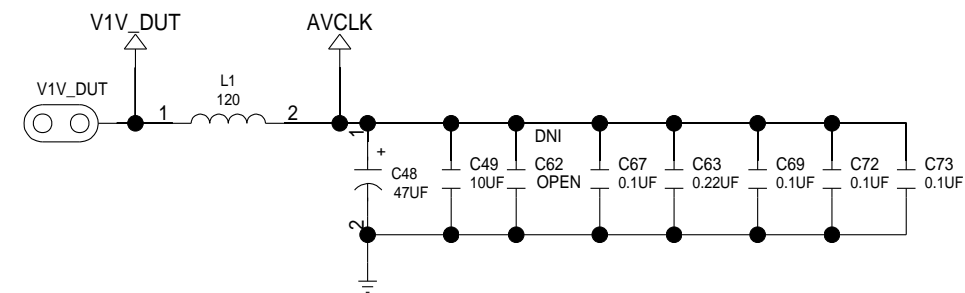
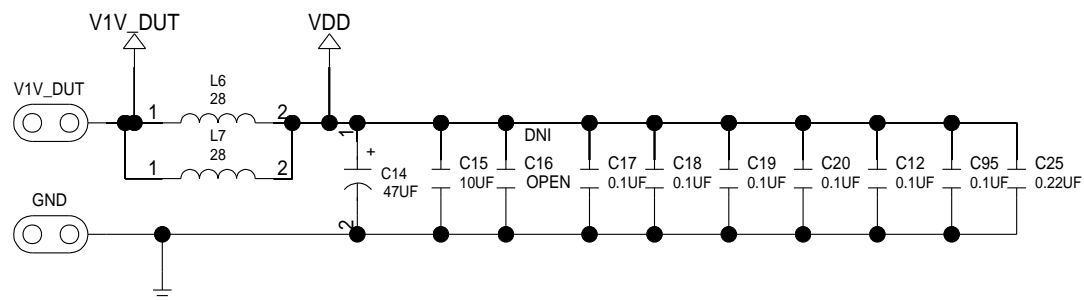


LAYOUT NOTES:

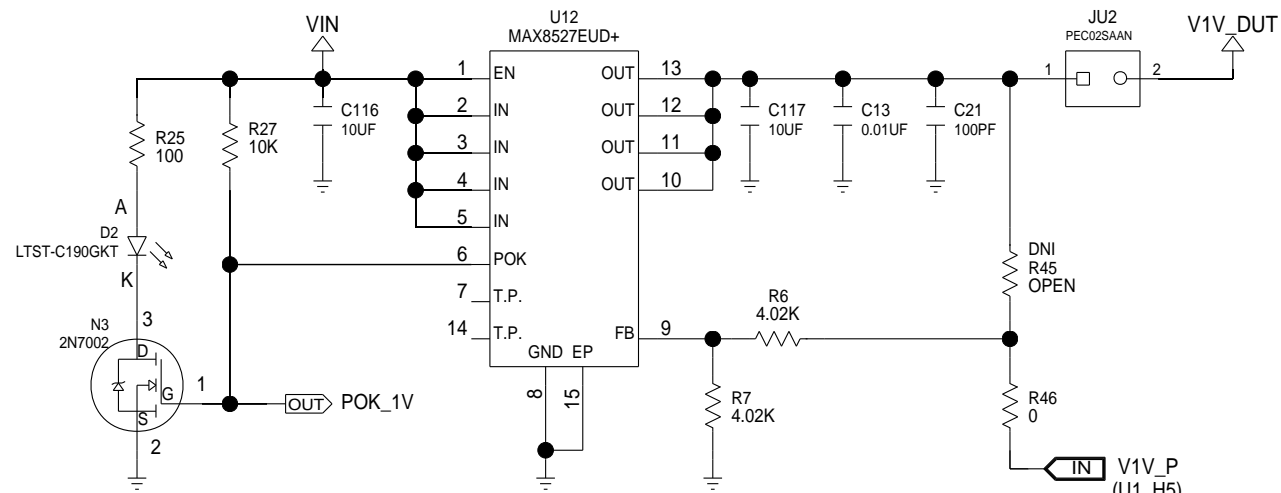
1. FLOOD TOP LAYER WITH GND, INCLUDING AROUND U1, TO MAXIMIZE THERMAL CONDUCTIVITY FOR U1. HOWEVER, ALL VIAS MUST HAVE THERMAL RELIEF FOR EASE OF ASSEMBLY.

PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 1 OF 9

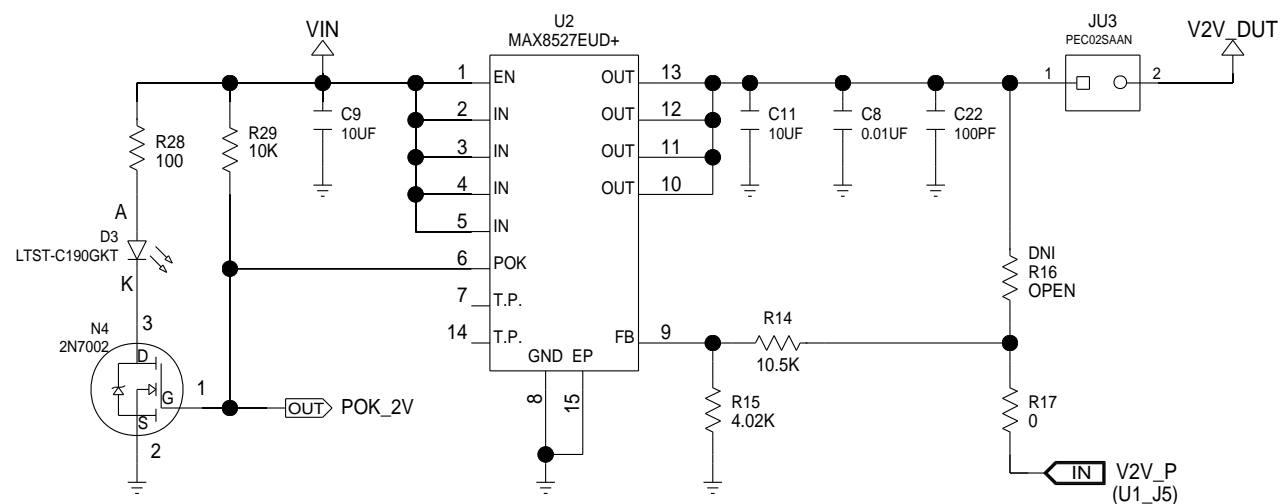


DEVICE POWER

DUT1V

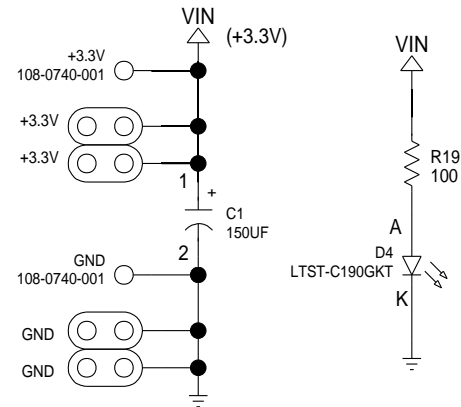


DUT1.8V

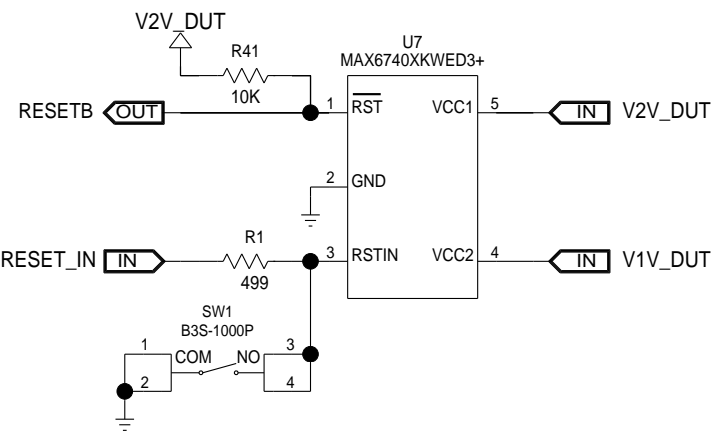


PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 2 OF 9

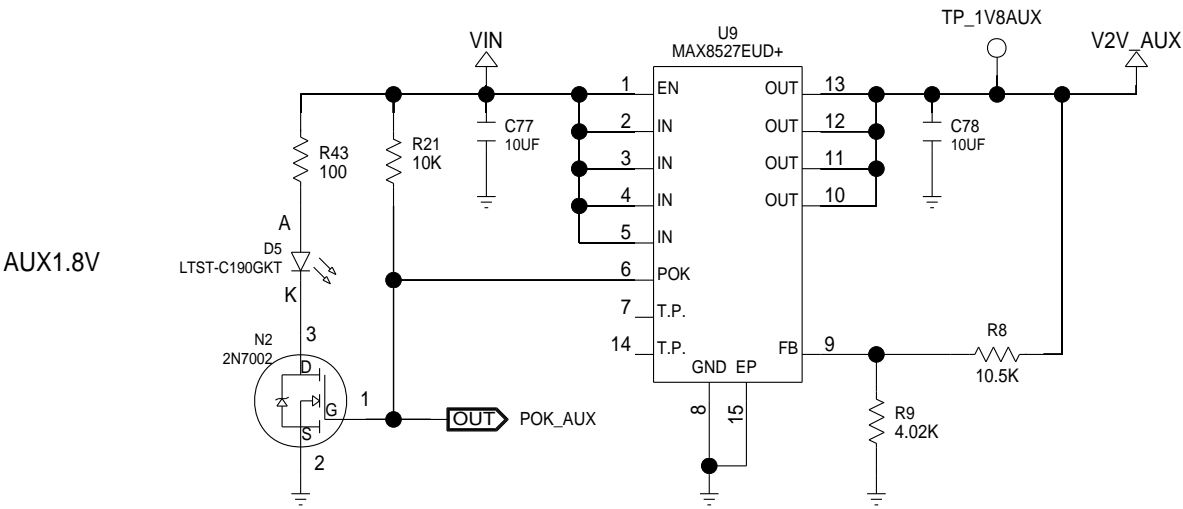
MAIN BOARD POWER



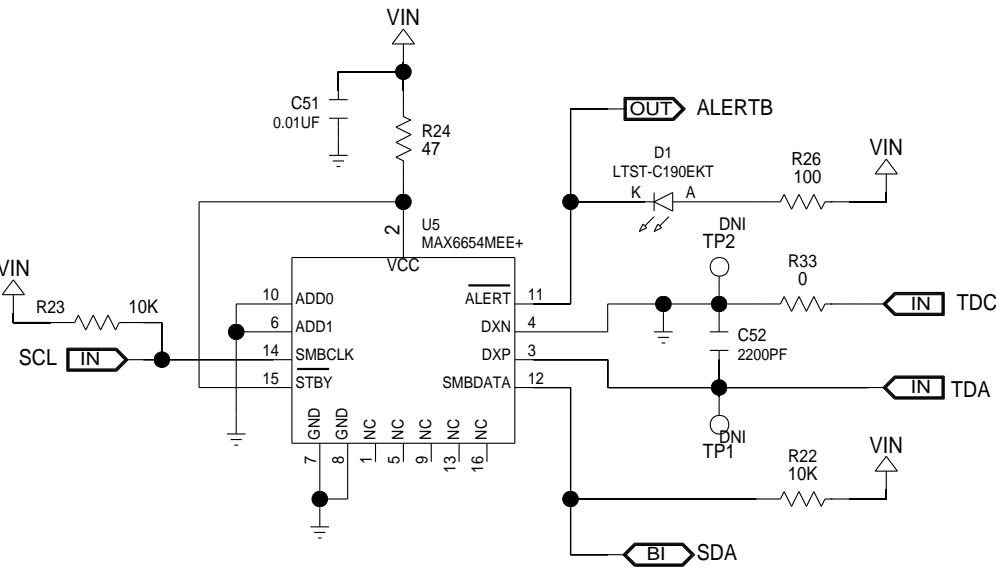
POWER ON RESET CIRCUIT



AUXILIARY POWER

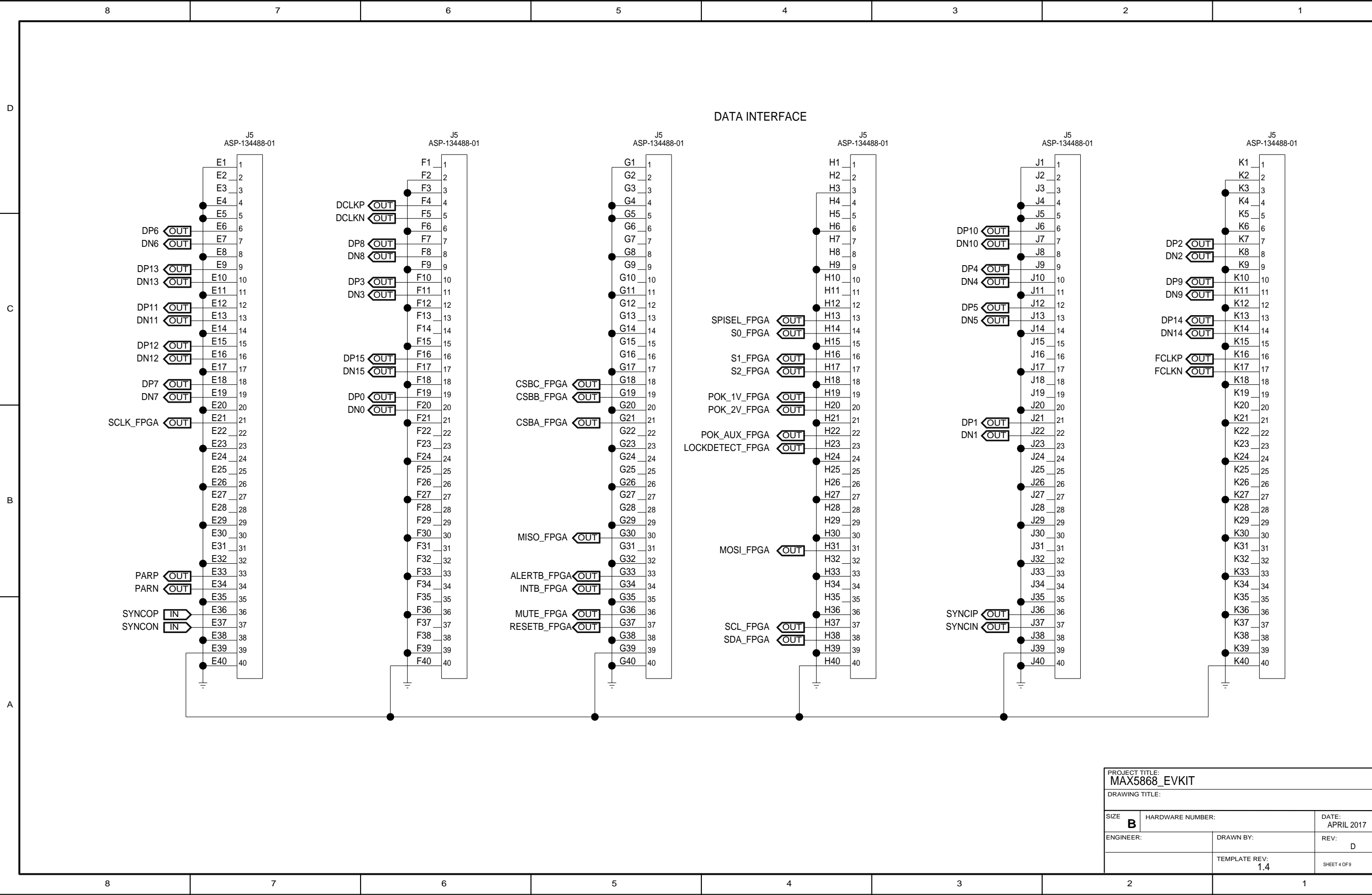


TEMPERATURE MONITOR

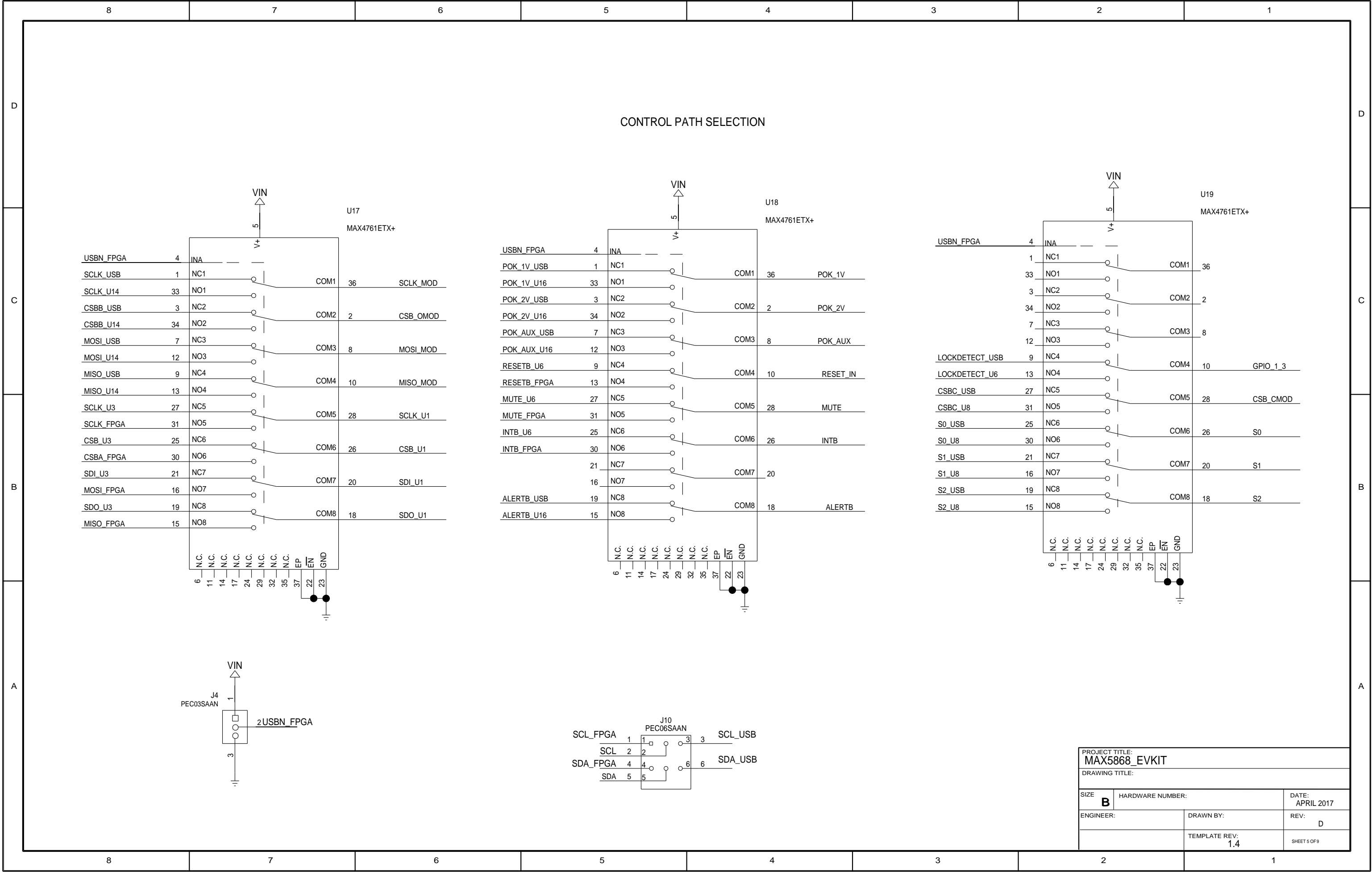


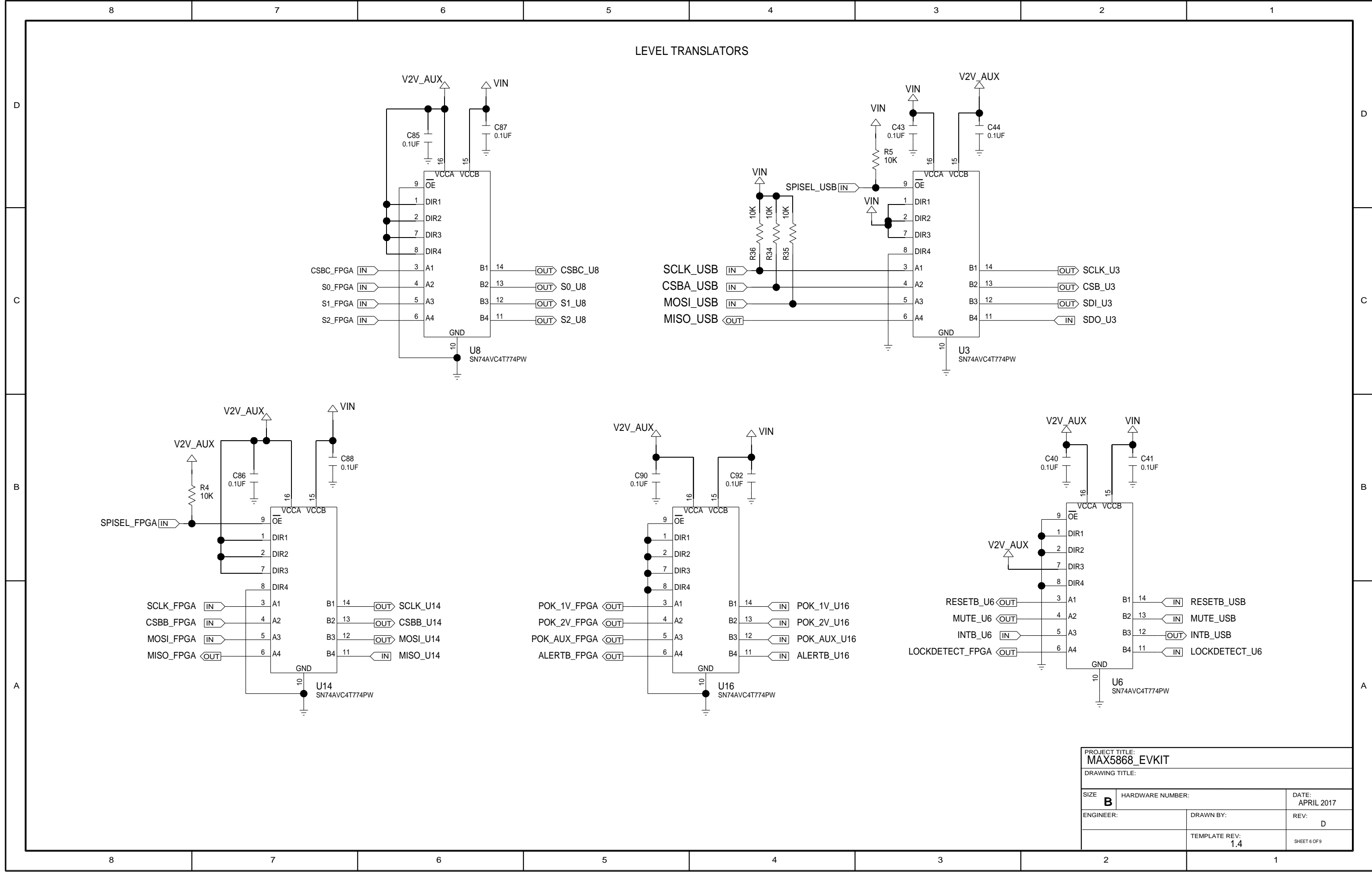
LAYOUT NOTES:
1. PLACE U5 CLOSE TO U1 TO MINIMIZE TRACES FOR TDC AND TDA.

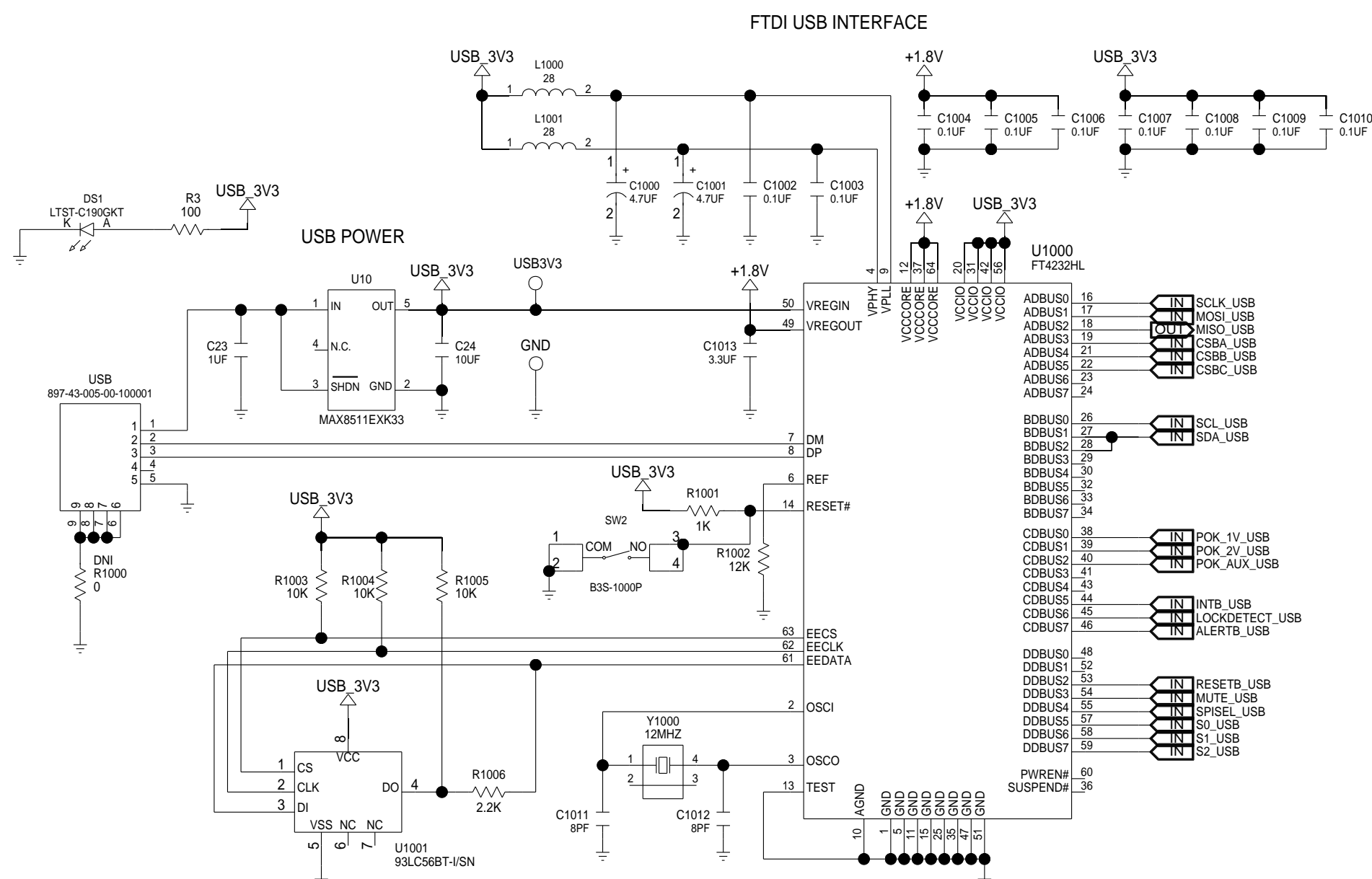
PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 3 OF 9



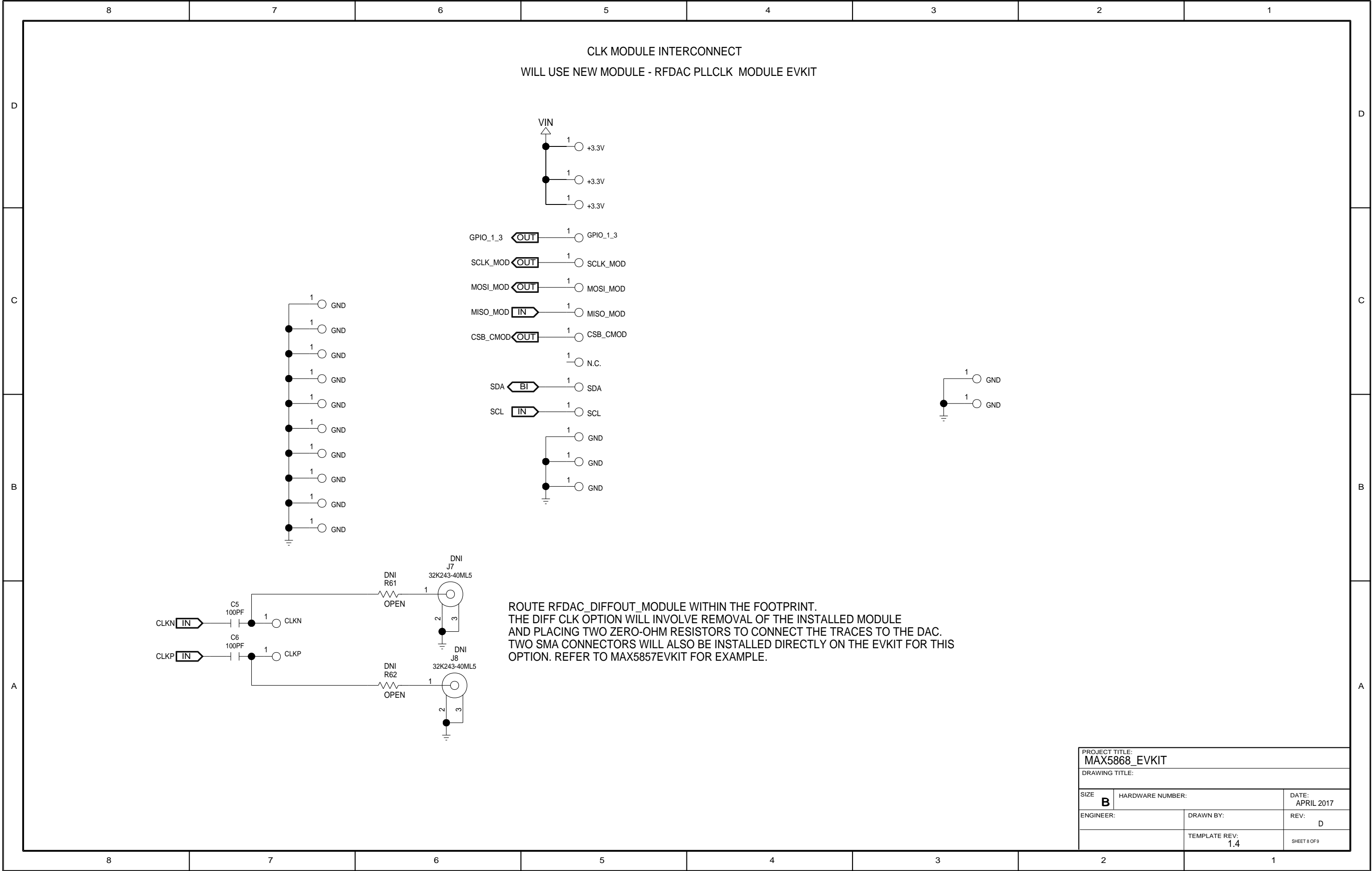
PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 4 OF 9







PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 7 OF 9



PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 8 OF 9

DAC OUT MODULE INTERCONNECT

OUTP IN

OUTN IN

AVDD2

C29 1UF

C30 1UF

L8 2.2UH

L9 2.2UH

OUTP

OUTN

DNI

C83 OPEN

DNI J2

32K243-40ML5

OUTP

DNI

C55 OPEN

DNI J6

32K243-40ML5

OUTN

GND

ROUTE RFDAC_DIFFOUT_MODULE WITHIN THE FOOTPRINT.
THE DIFF OUT OPTION WILL INVOLVE REMOVAL OF THE INSTALLED MODULE
AND PLACING TWO ZERO-OHM RESISTORS TO CONNECT THE TRACES TO THE DAC.
TWO SMA CONNECTORS WILL ALSO BE INSTALLED DIRECTLY ON THE EVKIT FOR THIS
OPTION. REFER TO MAX5857EVKIT FOR EXAMPLE.

VIN

+3.3V

+3.3V

CSB_MOD OUT

MOSI_MOD OUT

SCLK_MOD OUT

MISO_MOD OUT

N.C.

SDA BI

SCL IN

FOR EXPANSION PURPOSES

PROJECT TITLE: MAX5868_EVKIT		
DRAWING TITLE:		
SIZE B	HARDWARE NUMBER:	DATE: APRIL 2017
ENGINEER:	DRAWN BY:	REV: D
	TEMPLATE REV: 1.4	SHEET 9 OF 9

[illegible][illegible][illegible]